GHz MLF Socket - Direct mount, solderless

Features

- arget PCB (needs tooling holes) with hardware.
- Elastomer connection
- e required
- distributes forces evenly
- ver compression of elastomer
- wivel socket lid

Socket Lid: Black anodized Aluminum. Thickness = 2.5mm.



Socket base: Black anodized Aluminum. Thickness = 5mm.



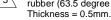
Compression Plate: Black anodized Aluminum. Thickness = 3.0mm.



Compression screw: Clear anodized Aluminum. Thickness = 5mm, Hex socket = 3mm.



Elastomer: 20 micron dia gold plated brass filaments arranged symmetrically in a silicone rubber (63.5 degree angle).



Elastomer Guide: Cirlex Thickness = 0.475mm.



IC (MLF) Guide: Ultem1000



Socket base screw: Socket head cap, Alloy steel with black oxide finish, 0-80 fine thread, 9.525mm long.



Socket lid screw: Shoulder screw, 18-8 SS, 0-80 fine



thread.



Socket base nut: 18-8 Stainless steel, 0-80 fine thread.

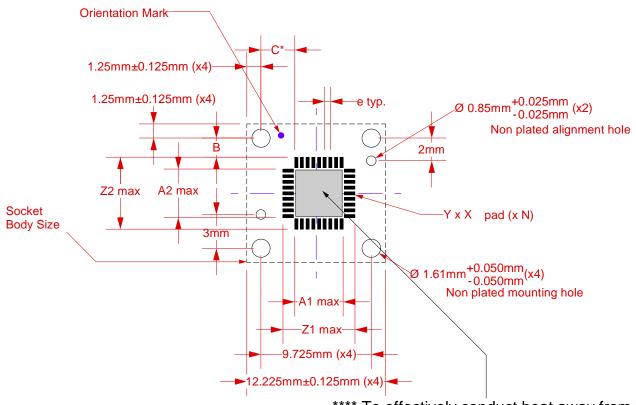
Nylon washer: 1.73mm ID; 4.78mm OD 0.64mm thickness.

T		realules
		 Directly mounts to ta
		 High speed, reliable
		Minimum real estate
		Compression plate d
		IC guide prevents over
12.225mm		 Easily removable swi
А		A
<u> </u>		
Side View (Section AA)		<u></u>
(Section AA)	12.225mm	•
Assembled 8.25mm +		Recommended torque = 1.0 in. lb. (16 in. oz.)
8.25mm + IC thickness		2
		8 77
	Customer's MLF	Customor's Target PCR
	IVILI	Customer's Target PCB

	SG-MLF-7005 Drawing	Status: Released Scal		: -	Rev: F
	© 2009 IRONWOOD ELECTRONICS, INC. Tele: (952) 229-8200 www.ironwoodelectronics.com	Drawing: H. Hansen		Date: 10/22/02	
		File: SG-MLF-7005 Dwg.mcd		Modified: 6/2	26/09, AE

All tolerances: ±0.125mm (unless stated otherwise). Materials and specifications are subject to change without notice.

*Note: MLF pattern is not symmetrical with respect to the mounting holes. It is offset 0.25mm to the right of center.



**** To effectively conduct heat away from the package a thermal pad is recommended with vias spaced 1.0 to 1.2 mm pitch and a diameter of 0.3 to 0.33 mm. Ideally 1 via for every 3 leads has been shown to work well.

Target PCB Recommendations
Total thickness: 1.6mm min.
Plating: Gold or Solder finish

PCB Pad height: Same or higher than solder mask

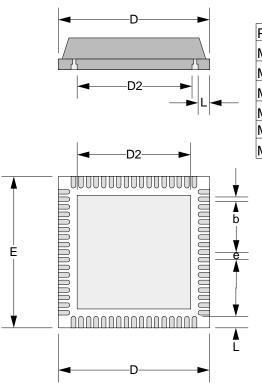
NOTE: Steel backing plate may be required based on end user's application

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Package Code	С	В	Z1max	A1max	Z2max	A2 max	е	Х	Y	N	Thermal Pad Recommendations
MLF36A	2.97	1.68	6.36	4	6	4	0.5	0.28	0	36	4.08 x 4.08
MLF40A	2.72	1.68	6.36	4 .78	6 .36	4 .78	0.5	0.28	p .69	40	4.58 x 4.58
MLF28B	2.98	1.68	6.36	<u>8</u> .27	6 .36	8 .27	0.65	0.37	0 .95	28	3.08 x 3.08
MLF20C	3.3	1.68	6.36	3.62	6.36	3.62	0.8	0.42	1.06	20	3.84 x 3.84
MLF48G	2.813	1.763	6.2	4.6	6.2	4.6	0.4	0.2	0.6	48	4.1 x 4.1
MLF32D	2.663	1.72	6.29	4.9	6.29	4.9	0.65	0.35	0.6	32	4.3 x 4.3

Recommended PCB Layout Tolerances: ±0.025mm unless stated otherwise.

All dimensions are in mm.



Package Code	е	D min	D max	E min	E max	b min	b max	L min	L max	D2	N
MLF36A	0.5	5.85	6.15	5.85	6.15	0.18	0.3	0.5	0.75	4.18	36
MLF40A	0.5	5.85	6.15	5.85	6.15	0.18	0.3	0.3	0.5	4.68	40
MLF28B	0.65	5.85	6.15	5.85	6.15	0.23	0.35	0.5	0.75	4.17	28
MLF20C	0.8	5.85	6.15	5.85	6.15	0.28	0.4	0.5	0.75	3.94	20
MLF48G	0.4	5.85	6.15	5.85	6.15	0.15	0.25	0.3	0.5	4.1	48
MLF32D	0.65	5.85	6.15	5.85	6.15	0.25	0.35	0.35	0.45	4.3	32

	SG-MLF-7005 Drawing	Status: Released	Scale	Scale: 3:1 Rev: F	
Tele: (9	© 2009 IRONWOOD ELECTRONICS, INC.	Drawing: H. Hansen		Date: 10/22/02	
	Tele: (952) 229-8200 www.ironwoodelectronics.com	File: SG-MLF-7005 Dwg.mcd		Modified: 6/26/09, AE	